

SUNLEI TECHNOLOGY CORP.

Multilayer Ferrite Bead Array-JA Series

JA series Bead Array For High Density Circuit Design

Multilayer bead array JA Series provides noise attenuation for four lines and is ideal for high density circuit design, such as LCD monitors, motherboard and so on.

Features

1. These multi-layered chip bead arrays are surface mount EMI components.
2. four lines in one chip for suppressing noise.
3. suitable for high density circuit design



Applications

Computers. LCD Monitor
Hard Disk Drive. CD-ROMs. Motherboard

Product Identification

JA 3216U- 121 - PF

JA: SERIES NAME

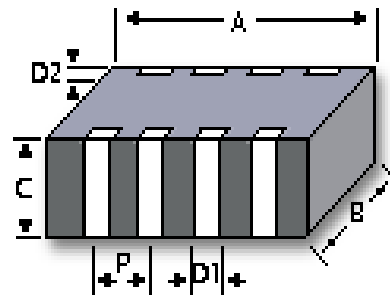
3216: DIMENSION SIZE CODE

U: Material Type CODE

121: IMPEDANCE CODE.

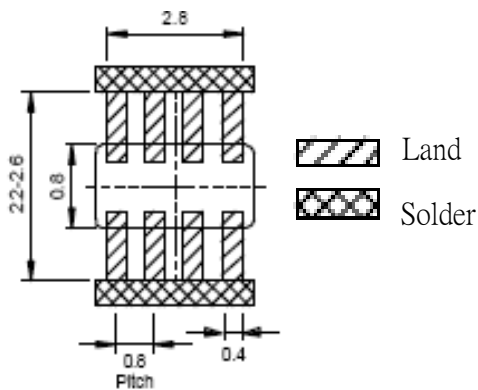
PF: Pb Free

Dimensions (mm)



SERIES	A	B	C	D1	D2	P
JA3216	3.2±0.2	1.6±0.2	0.9±0.2	0.4±0.2	0.35±0.2	0.8±0.1

Recommended Pattern(mm)



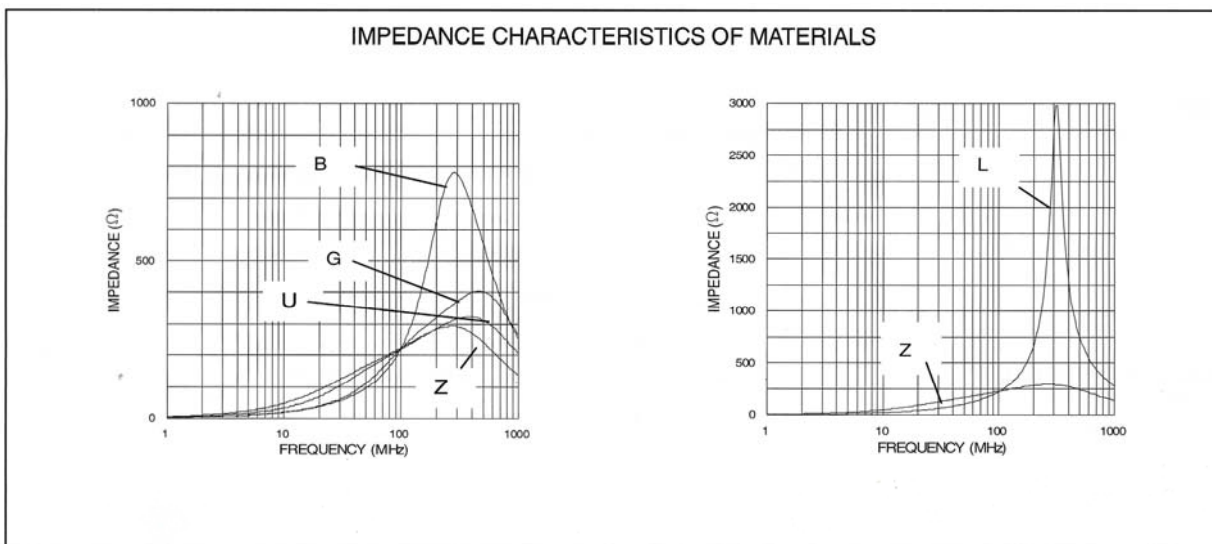
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Multilayer Chip Inductors-JA Series

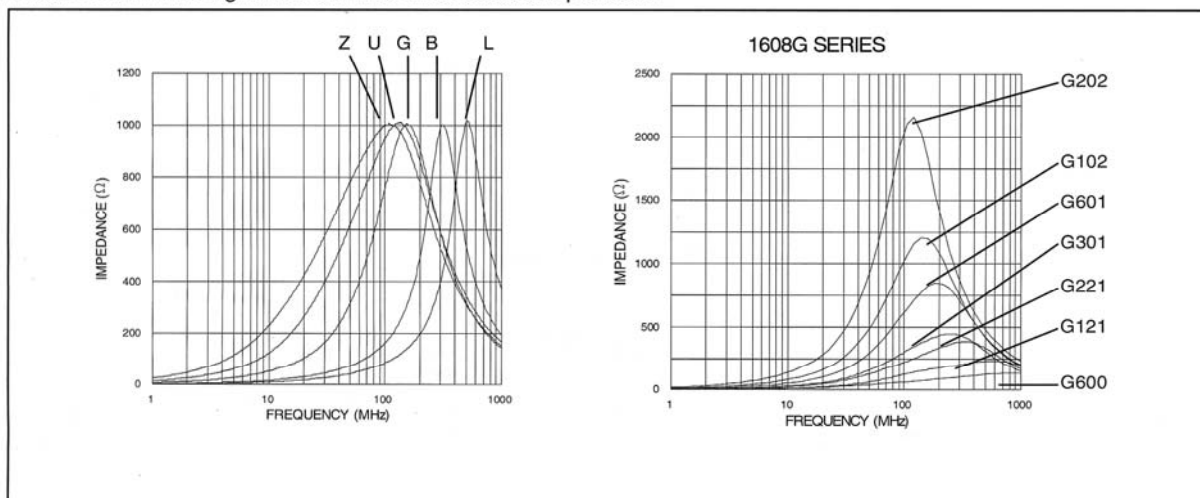
JA series Bead Array For High Density Circuit Design

MATERIAL CHARACTERISTICS

ITEM	UNIT	Material Code				
		L	B	G	U	Z
Initial Permeability μ_{iac}	-	25	45	110	200	500
Maximun Permeability μ_M	-	125	125	250	450	900
Saturation Flux Density at 10 Oe B_s	Gauss	2000	2000	1700	1400	1500
Curie Temperature T_c	$^{\circ}C$	> 200	> 200	> 130	> 130	> 100
Volume Resistivity ρ	$\Omega\text{-m}$	105	105	105	105	105
Temperature Coefficient(Inductance)	$10^{-4}/^{\circ}C$	10		12	13	5
Density	g/cm^3	4.8		4.8	4.8	4.8



- ◇ Z Material is for applications whose blocking region is near 100 MHz.
- ◇ L material, an improvement of B material, has sharp impedance characteristics at high frequency.
- ◇ G material is for application whose signal frequency is far from the cut off region. Suitable for application requires low insertion loss at high frequency.
- ◇ Please confirm the signal waveform to choose suitable products.



- ◇ Different materials are available for different application range.
- ◇ With one material, higher impedance has sharper characteristics.

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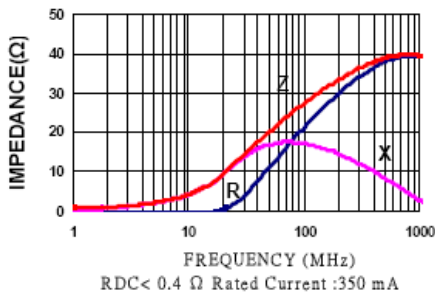
Multilayer Ferrite Bead Array-JA Series

JA series Bead Array For High Density Circuit Design

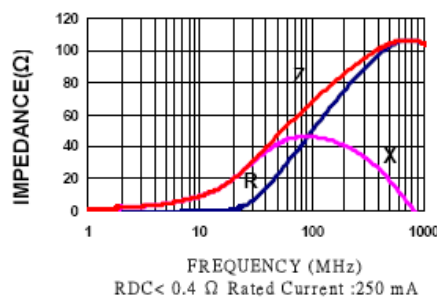
Part Number	Test Frequency (MHz)	Impedance ($\Omega \pm 25\%$)	DC Resistance (Ω)max	Rated current (mA)max
JA321609U-300-PF	100	30	0.40	350
JA321609U-600-PF	100	60	0.40	250
JA321609U-121PF	100	120	0.80	150
JA321609U-241-PF	100	240	0.80	150
JA321609U-301-PF	100	300	0.80	150
JA321609U-471-PF	100	470	1.00	100
JA321609U-601-PF	100	600	1.50	100
JA321609U-102-PF	100	1000	1.70	50
JA321609G-600-PF	100	60	0.80	150
JA321609G-121-PF	100	120	0.80	150
JA321609G-221-PF	100	220	0.80	150
JA321609G-471-PF	100	470	1.00	150
JA321609G-601-PF	100	600	1.50	100
JA321609G-102-PF	100	1000	1.80	100

Test Instruments:HP4291A Impedance / Material Analyzer

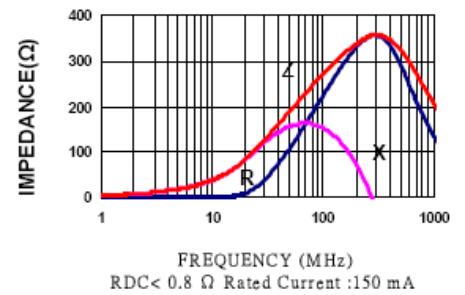
JA321609U-300-PF



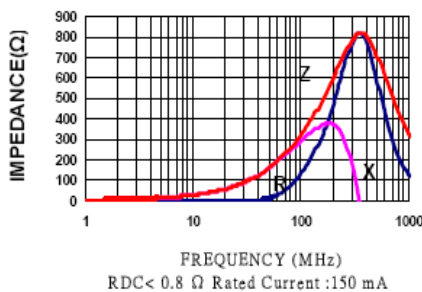
JA321609U-600-PF



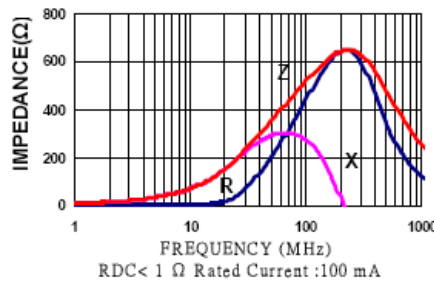
JA321609U-241-PF



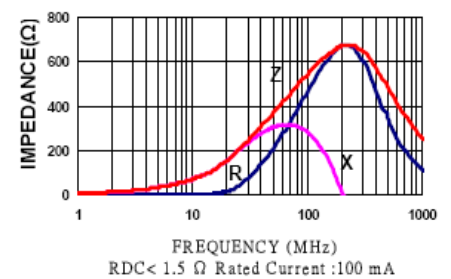
JA321609U-301-PF



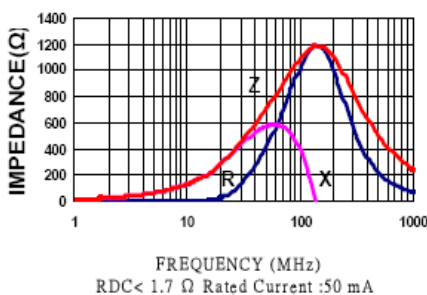
JA321609U-471-PF



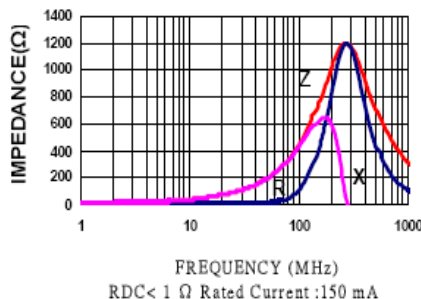
JA321609U-601-PF



JA321609U-102-PF

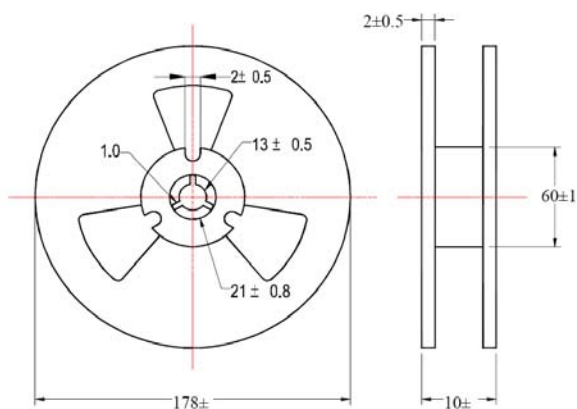


JA321609G-471-PF

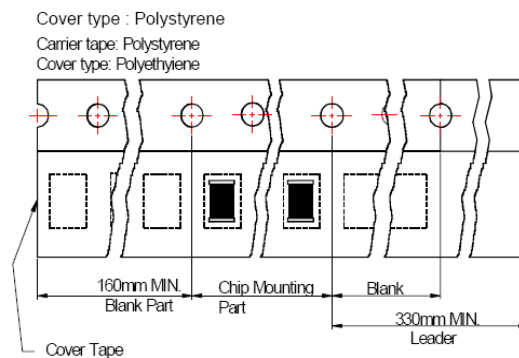


PACKAGING

REEL Dimensions (mm)



TAPE Material



Carrier Tape: Polystyrene (for 201209, 201212, 321611 series)
Paper (for 160808)

Tape Dimensions (mm)

Figure A

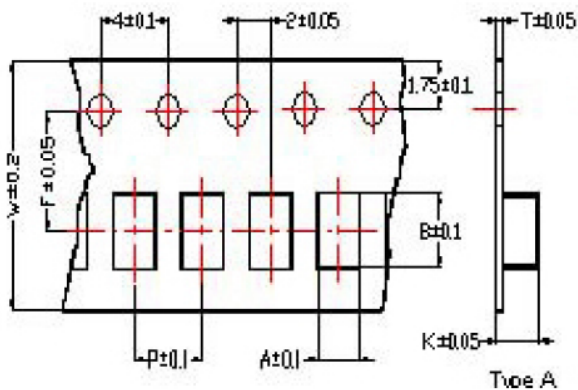
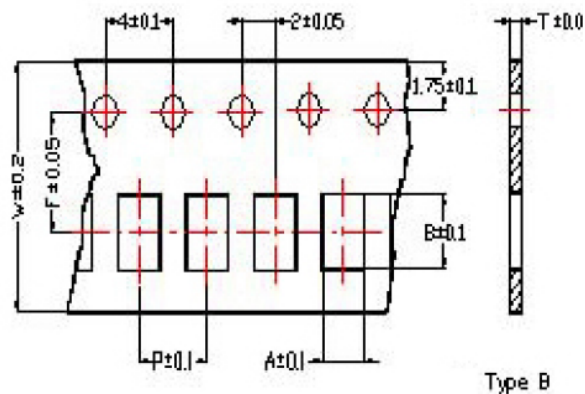


Figure B



TAPE DIMENSIONS AND PACKAGING QUANTITIES

TYPE	A	B	W	P	T	CHIPS / REEL
321611	1.94	3.54	8	4	0.2	3000